



RF360
Europe GmbH

SAW components

SAW Rx filter

Automotive telematics
LTE band 1

Series/type:	B4359
Ordering code:	B39212B4359P810
Date:	December 22, 2016
Version:	2.0

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Data sheet

Table of contents

1	Application	3
2	Features	3
3	Package	4
4	Pin configuration	4
5	Matching circuit	5
6	Characteristics	6
7	Maximum ratings	7
8	Transmission coefficient	8
9	Reflection coefficients	9
10	Packing material	10
11	Marking	13
12	Soldering profile	14
13	ESD protection of SAW filters	15
14	Annotations	16
15	Cautions and warnings	17
	Important notes	18

Data sheet

1 Application

- Low-loss RF filter for LTE Band 1 systems (Rx)
- Usable pass band 60MHz

2 Features

- Package size 1.4±0.1 mm × 1.1±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family
(Grade 1: -40 °C to +125 °C)

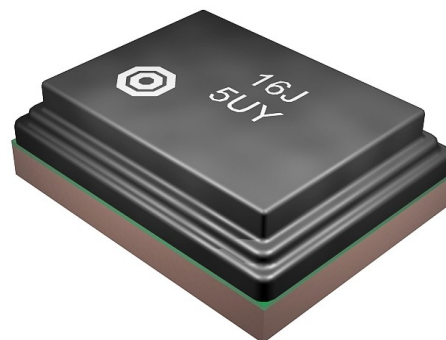
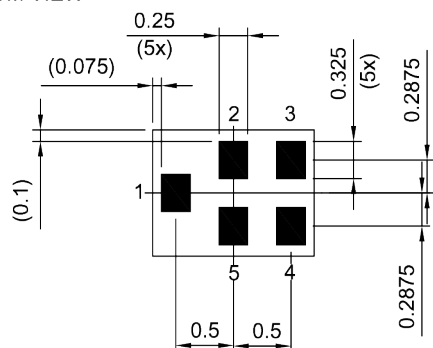


Figure 1: Picture of component with example of product marking.

Data sheet

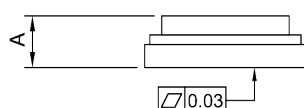
3 Package

BOTTOM VIEW

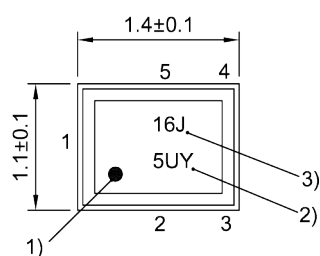


Pad and pitch tolerance ±0.05

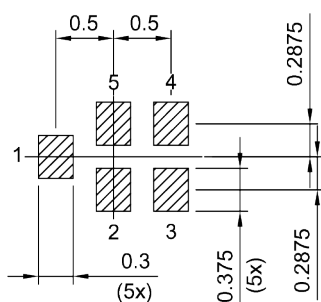
SIDE VIEW



TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW


Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 17).

4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

Data sheet

5 Matching circuit

■ $L_{p4} = 15 \text{ nH}$

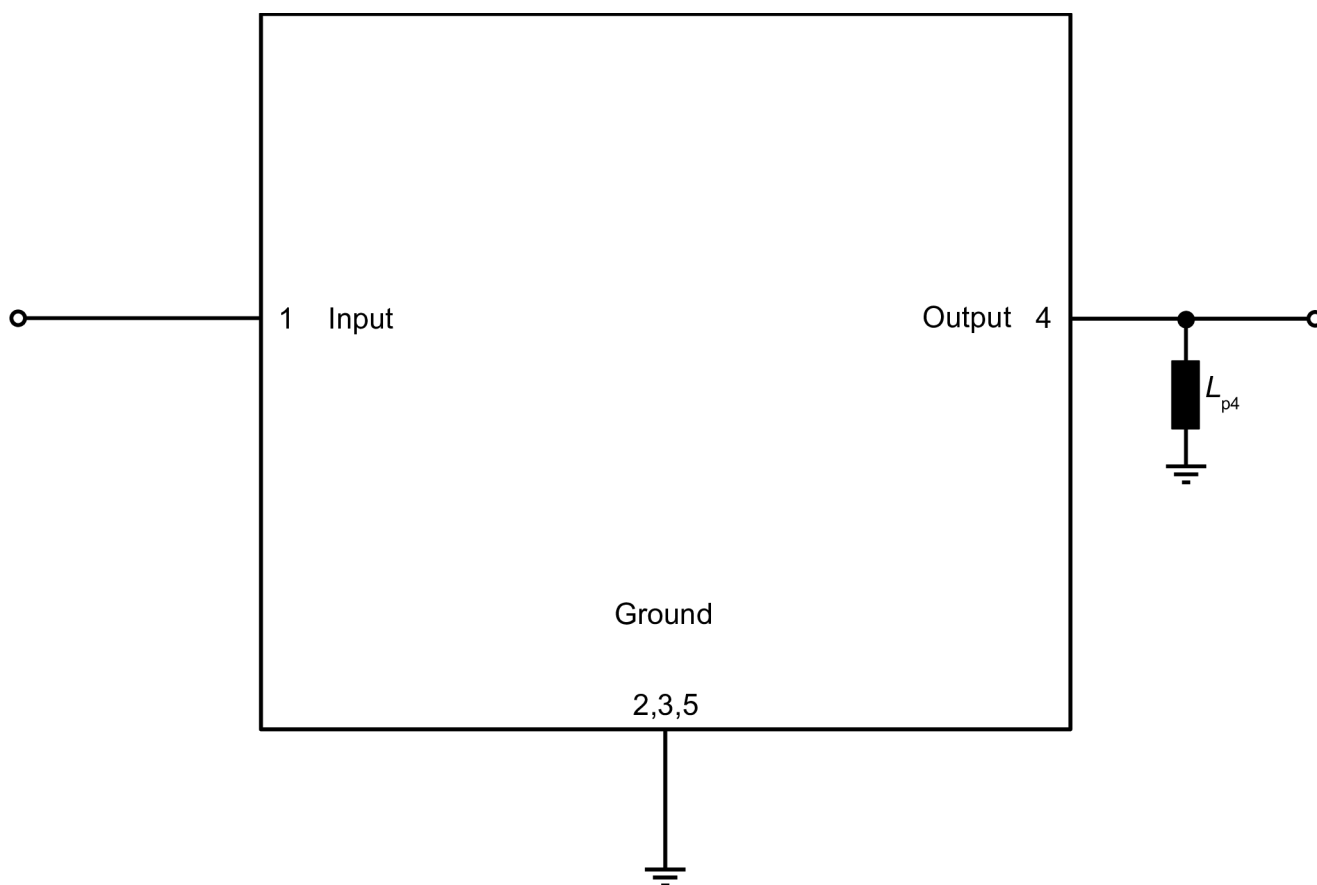


Figure 3: Schematic of matching circuit.

SAW components	B4359
SAW Rx filter	2140 MHz

Data sheet

6 Characteristics

Temperature range for specification	T_{SPEC}	= -30 °C ... +85 °C
Input terminating impedance	Z_{IN}	= 50 Ω
Output terminating impedance	Z_{OUT}	= 50 Ω with par. 15 nH ¹⁾

Characteristics			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency		f_{C}	—	2140	—	MHz
Maximum insertion attenuation		α_{max}	—	2.2	2.4	dB
	2110... 2170	MHz	—	2.2	2.4	dB
Amplitude ripple (p-p)		$\Delta\alpha$	—	0.8	1.1	dB
	2110... 2170	MHz	—	0.8	1.1	dB
Maximum VSWR		VSWR_{max}	—	1.8	2.3	
@ input port	2110... 2170	MHz	—	1.8	2.3	
@ output port	2110... 2170	MHz	—	2.1	2.5	
Minimum attenuation		α_{min}				
	10... 1710	MHz	40	50	—	dB
	1710... 1755	MHz	40	55	—	dB
	1755... 1920	MHz	40	55	—	dB
	1920... 1980	MHz	40	48	—	dB
	1980... 2045	MHz	35	41	—	dB
	2045... 2075	MHz	11	20	—	dB
	2255... 2400	MHz	37	41	—	dB
	2400... 2500	MHz	40	47	—	dB
	2500... 4240	MHz	39	42	—	dB
	4240... 4340	MHz	37	41	—	dB
	4340... 6000	MHz	36	40	—	dB

¹⁾ See Sec. Matching circuit (p. 5).

SAW components	B4359
SAW Rx filter	2140 MHz

Data sheet

7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +125\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +125\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
Input power @ input port: 2110 ... 2170 MHz	$P_{IN} = 15\text{ dBm}$	Continuous wave for 2000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

Data sheet

8 Transmission coefficient

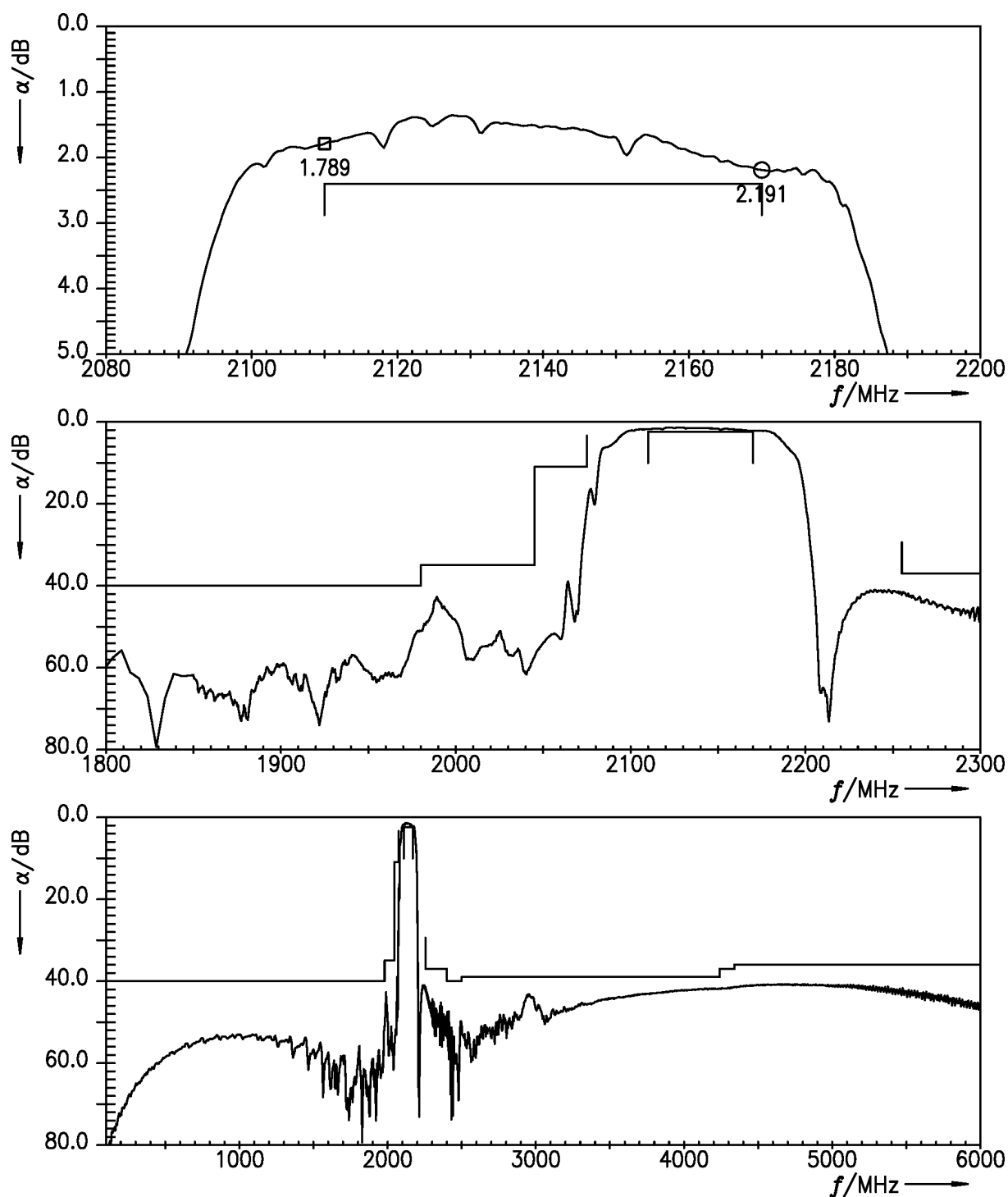


Figure 4: Attenuation.

Data sheet

9 Reflection coefficients

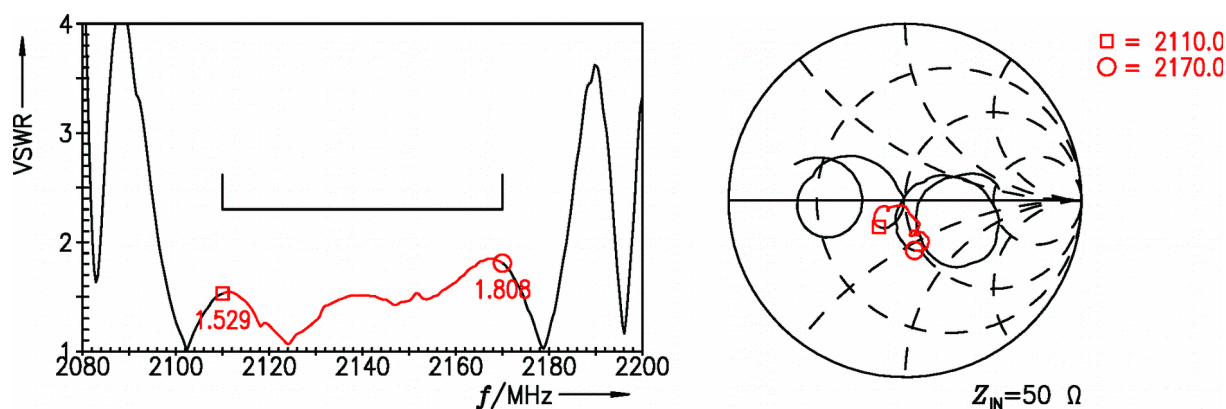


Figure 5: Reflection coefficient at IN port.

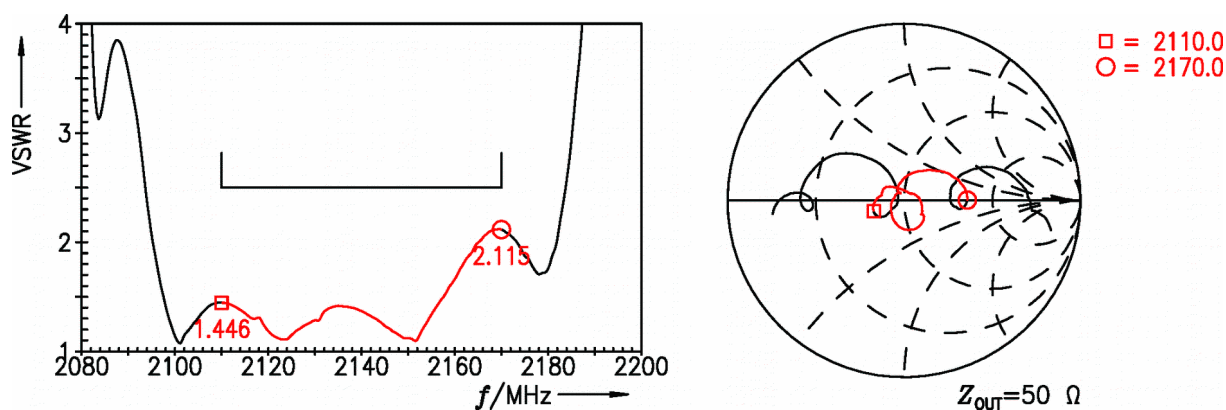


Figure 6: Reflection coefficient at OUT port.

Data sheet

10 Packing material

10.1 Tape

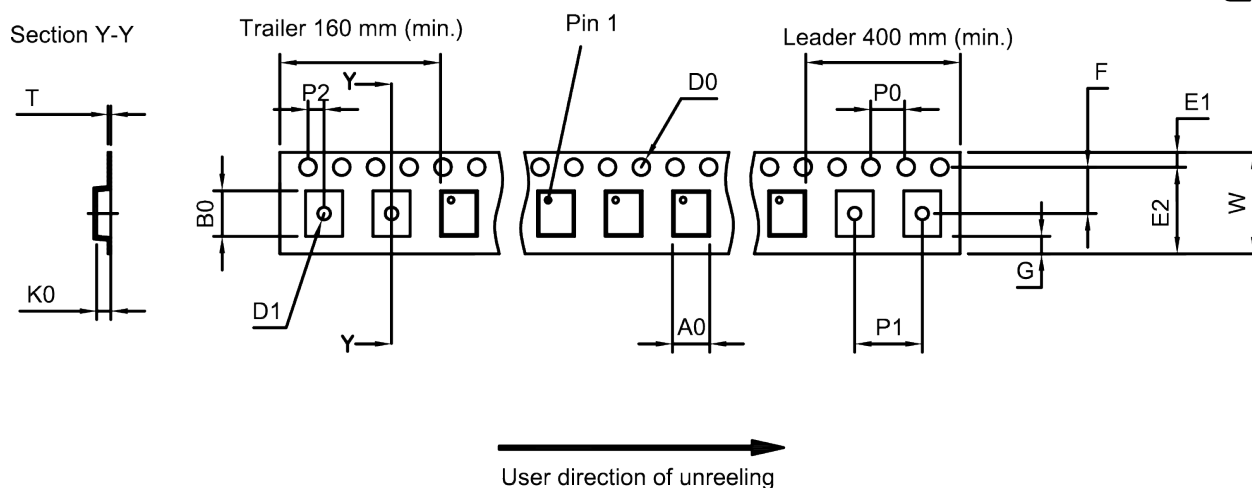


Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	1.27±0.05 mm
B ₀	1.57±0.05 mm
D ₀	1.5+0.1/-0 mm
D ₁	0.5±0.1 mm
E ₁	1.75±0.1 mm

E ₂	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K ₀	0.62±0.05 mm
P ₀	4.0±0.1 mm

P ₁	4.0±0.1 mm
P ₂	2.0±0.05 mm
T	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

Table 1: Tape dimensions.

Data sheet

10.2 Reel with diameter of 180 mm

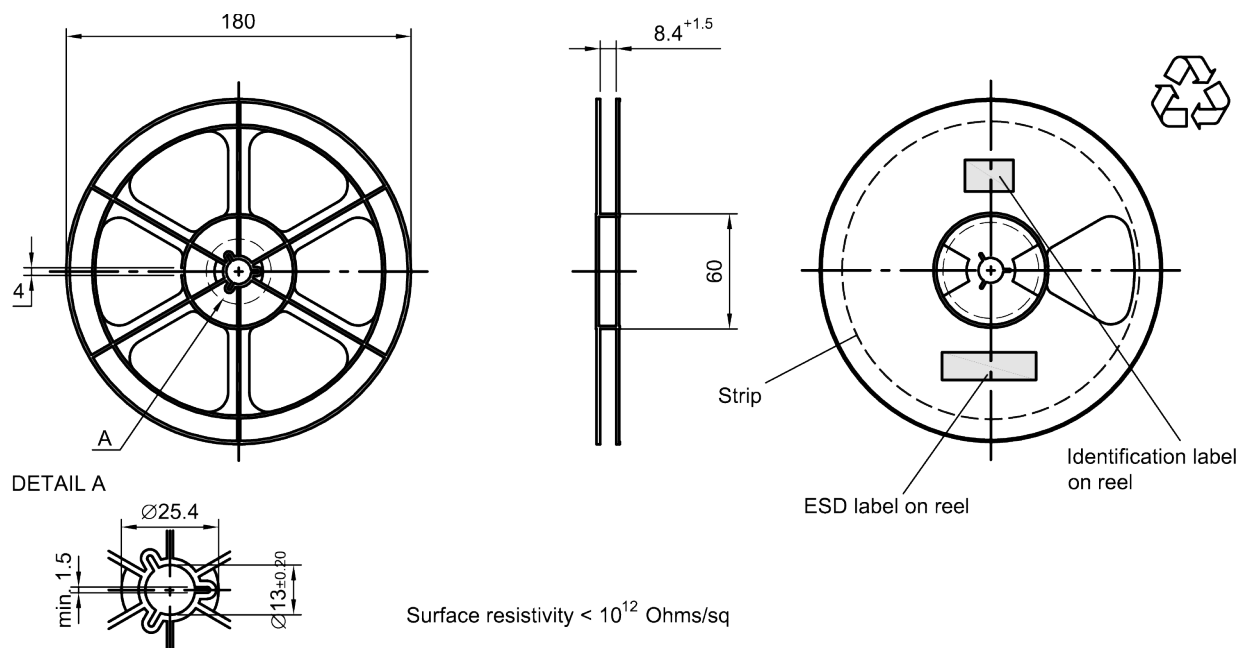


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220±5

Y = 235±5

Sealing area 10±3

Printing
on vacuumbag

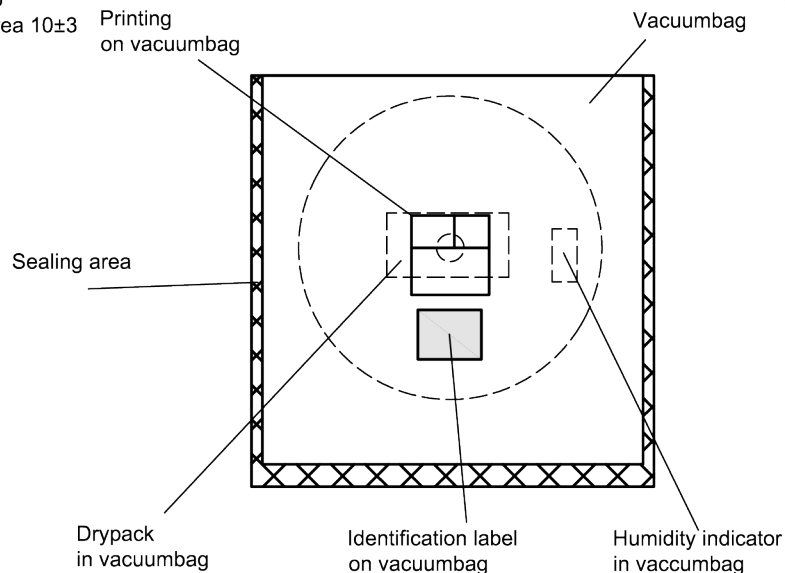


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Data sheet
Dimensions [mm]

L = 188

B = 188

H = 30

Tolerance ± 5

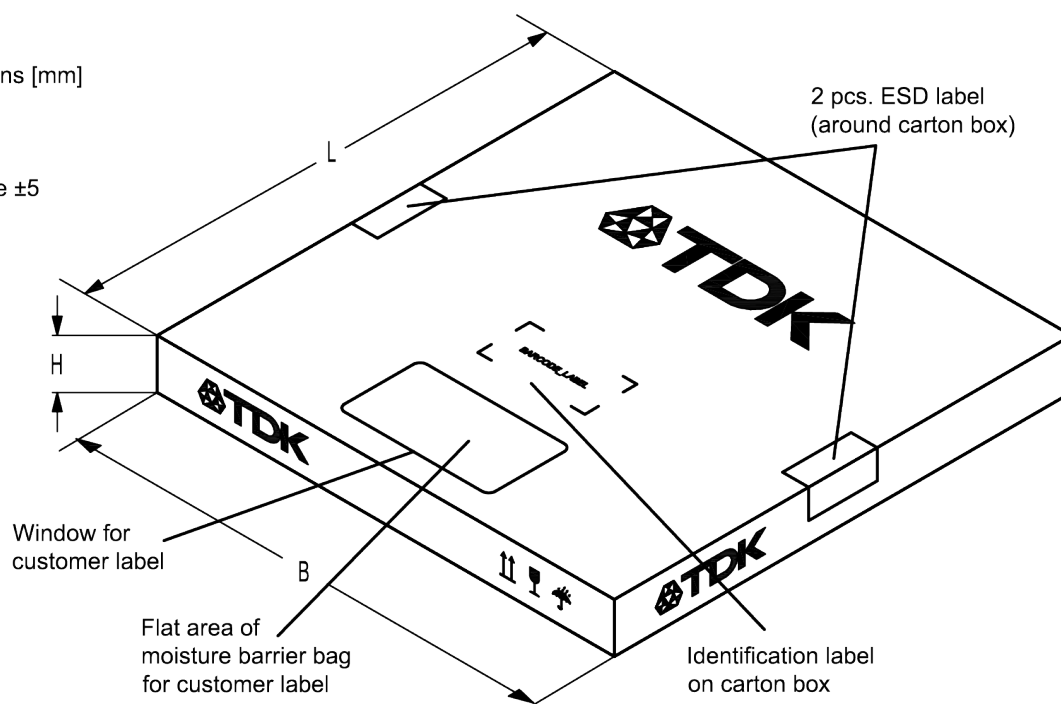


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

Data sheet

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

$$\begin{array}{rcl} \mathbf{16J} & \Rightarrow & \mathbf{1234} \\ \mathbf{1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0} & = & \mathbf{1234} \end{array}$$

The BASE32 code for product type B4359 is 487.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**, are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

$$\begin{array}{rcl} \mathbf{5UY} & \Rightarrow & \mathbf{12345} \\ \mathbf{5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0} & = & \mathbf{12345} \end{array}$$

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

SAW components	B4359
SAW Rx filter	2140 MHz

Data sheet

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	$\leq 3 \text{ K/s}$
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220 \text{ °C}$	30 s to 70 s
$T > 230 \text{ °C}$	min. 10 s
$T > 245 \text{ °C}$	max. 20 s
$T \geq 255 \text{ °C}$	–
peak temperature T_{peak}	250 °C $\pm 5 \text{ °C}$
wetting temperature T_{min}	230 °C $\pm 5 \text{ °C}$ for 10 s $\pm 1 \text{ s}$
cooling rate	$\leq 3 \text{ K/s}$
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

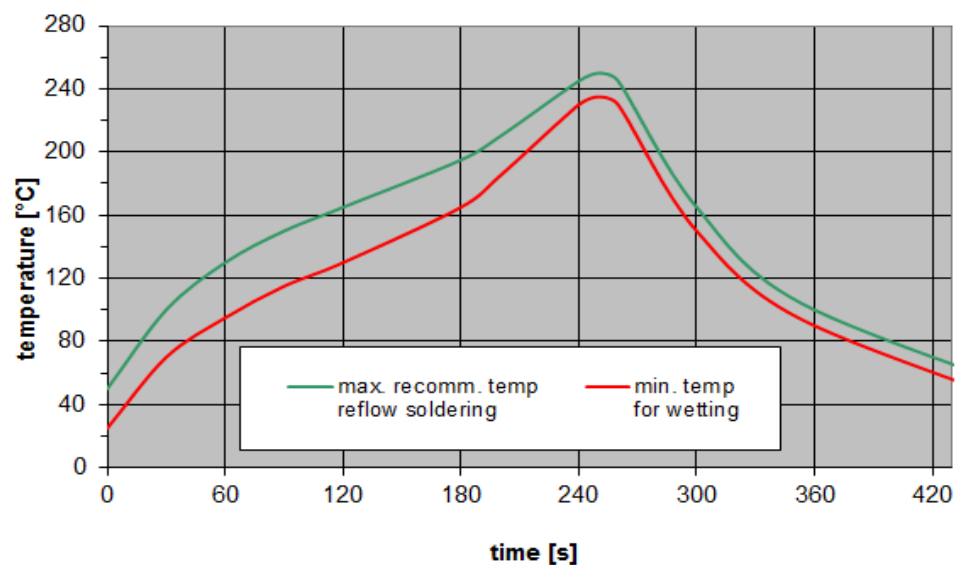


Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

Data sheet

13 ESD protection of SAW filters

SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

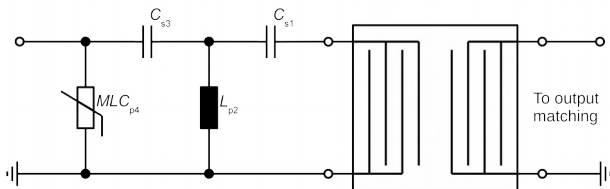


Figure 12: MLC varistor plus ESD matching.

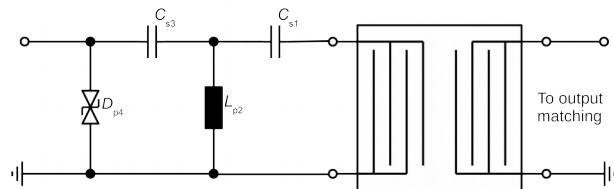


Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

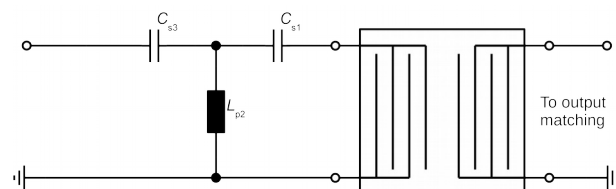


Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to EPCOS Application report: “**ESD protection for SAW filters**”. This report can be found under www.epcos.com/rke. Click on “Applications Notes”.

Data sheet

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

Data sheet

15 Cautions and warnings

15.1 Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

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